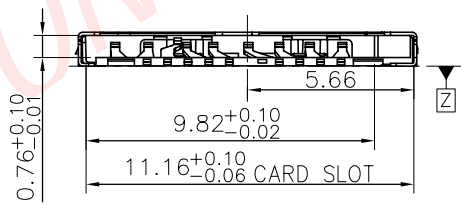
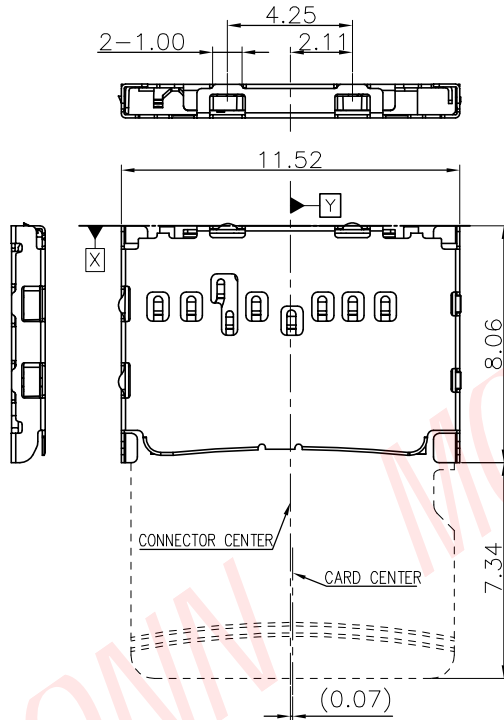
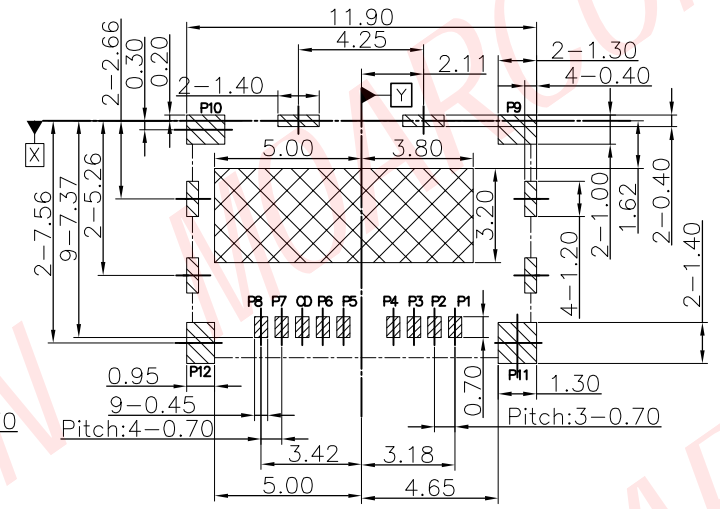
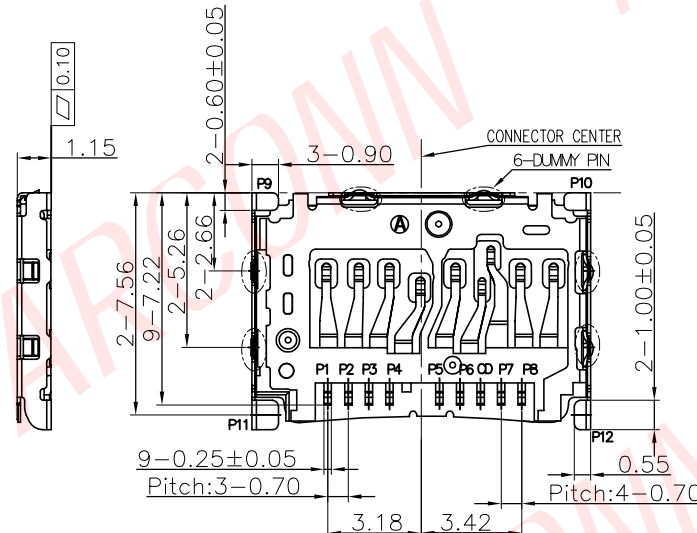
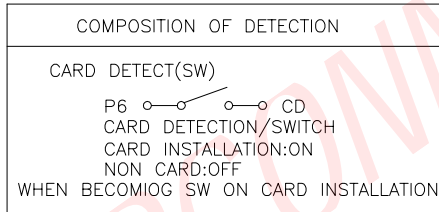


All materials, plating and process meet HF requirements.

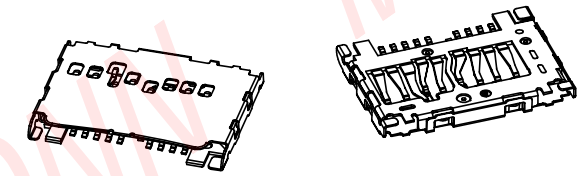


Pin Define	
P1	DAT2
P2	CD/DAT3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
CD	CARD DETECT
P7	DAT0
P8	DAT1
P9-P12	GND



RECOMMEND P.C.B LAYOUT
 (General tolerance ±0.05)

- PAD AREA
- KEEP OUT AREA
- NO COPPER AREA
- GND PATTERN ONLY



- NOTE:
- Material:
 - 1-1 Housing: High Temperature Thermoplastic, (LCP MG350) Color Black UL 94V-0.
 - 1-2 Contact: Phosphor Bronze (C5210R-SH T=0.12mm)
 - 1-3 Cover: SUS304-H T=0.10mm
 - Plating:
 - 2-1 Contact terminal: Contact area: Gold 2u" Min. Middle Pd-Ni 8u" min. Solder area: Gold 1u" Min. Underplating: Ni overall 80u" Min.
 - 2-2 Cover: Underplating: Ni overall 30u" Min. Solder area: Gold 1u" Min.
 - Specification:
 - 3-1. Contact Current Rating: 0.5 Amperes.
 - 3-2. Dielectric Withstanding Voltage: AC500V r.m.s.
 - 3-3. Insulation Resistance: 1000 Megohms Minimum At DC 500V.
 - 3-4. Contact Resistance: 100 mΩ Maximum.
 - 3-5. Mating Cycles: 5,000 Cycles.
 - 3-6. Operating Temperature: -25°C ~ +60°C.
 - Product Compliant to RoHS Directive 2002/95/EC and ELV 2000/53/EC
 - Recommending A Metal More Than 0.15mm Thick. Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
B	ER2101004	Modify the dimension	Alexander	2020.12.10
A	----	NEW RELEASE	pure	2020.07.11

		DONG GUAN MOARCONN ELECTRONIC Co., Ltd.			
		DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE	PRODUCT NAME : Micro SD H1.15 CARD (XNT)	DRAWING: Alexander	DATE: 2020.12.10
DIMENSION TOLERANCE X.X: ± 0.35 X.XX: ± 0.20 X.XXX: ± 0.10 ANGULAR: ± 2'	PRODUCT NO. : MS115-T7131-02	CHECK:	DATE:		
	DRAWING NO. : D-MS115-T7131-02	APPROVED:	DATE:		
		SCALE: 1:1	DWG ID: C D	REV.: B	PAGE: 1 OF 1